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# PMV75UP

20 V, P-channel Trench MOSFET

25 April 2014

Product data sheet

## 1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

## 2. Features and benefits

- Trench MOSFET technology
- Low threshold voltage
- Very fast switching
- Enhanced power dissipation capability:  $P_{tot} = 1000 \text{ mW}$

## 3. Applications

- LED driver
- Power management
- High-side loadswitch
- Switching circuits

## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$T_j = 25 \text{ }^\circ\text{C}$	-	-	-20	V
$V_{GS}$	gate-source voltage		-12	-	12	V
$I_D$	drain current	$V_{GS} = -4.5 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}; t \leq 5 \text{ s}$	[1]	-	-3.2	A
<b>Static characteristics</b>						
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = -4.5 \text{ V}; I_D = -2.5 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	77	102	m $\Omega$

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain  $6 \text{ cm}^2$ .



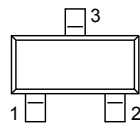
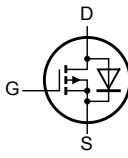
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## PMV75UP

20 V, P-channel Trench MOSFET

### 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 <p>TO-236AB (SOT23)</p>	 <p>017aaa257</p>
2	S	source		
3	D	drain		

### 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMV75UP	TO-236AB	plastic surface-mounted package; 3 leads	SOT23

### 7. Marking

Table 4. Marking codes

Type number	Marking code
PMV75UP	[1] %CN

[1] % = placeholder for manufacturing site code

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8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> = 25 °C		-	-20	V
V <sub>GS</sub>	gate-source voltage			-12	12	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 25 °C; t ≤ 5 s	[1]	-	-3.2	A
		V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 25 °C	[1]	-	-2.5	A
		V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 100 °C	[1]	-	-1.6	A
I <sub>DM</sub>	peak drain current	T <sub>amb</sub> = 25 °C; single pulse; t <sub>p</sub> ≤ 10 μs		-	-10	A
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C	[2]	-	490	mW
			[1]	-	1000	mW
		T <sub>sp</sub> = 25 °C		-	5000	mW
T <sub>j</sub>	junction temperature			-55	150	°C
T <sub>amb</sub>	ambient temperature			-55	150	°C
T <sub>stg</sub>	storage temperature			-65	150	°C
<b>Source-drain diode</b>						
I <sub>S</sub>	source current	T <sub>amb</sub> = 25 °C	[1]	-	-0.9	A

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm<sup>2</sup>.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

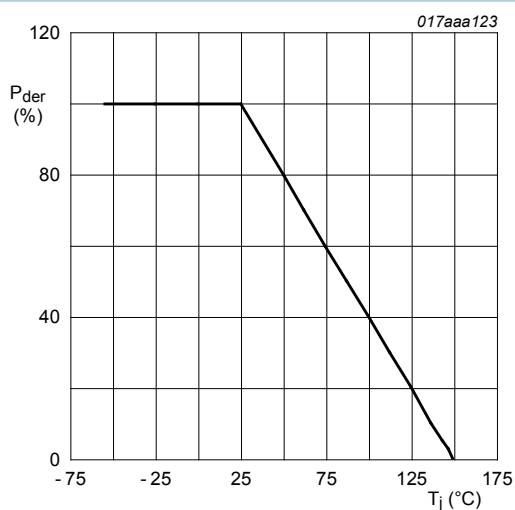


Fig. 1. Normalized total power dissipation as a function of junction temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100 \%$$

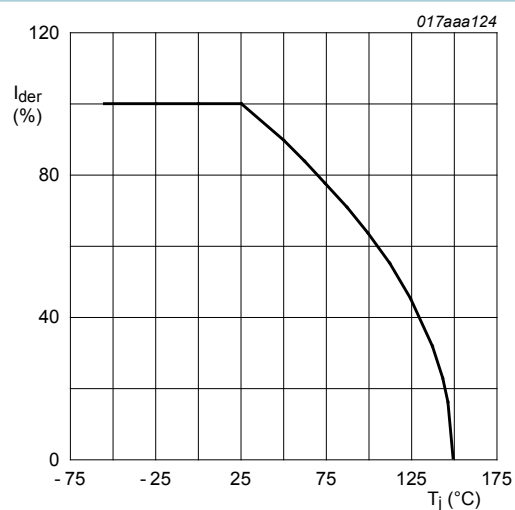
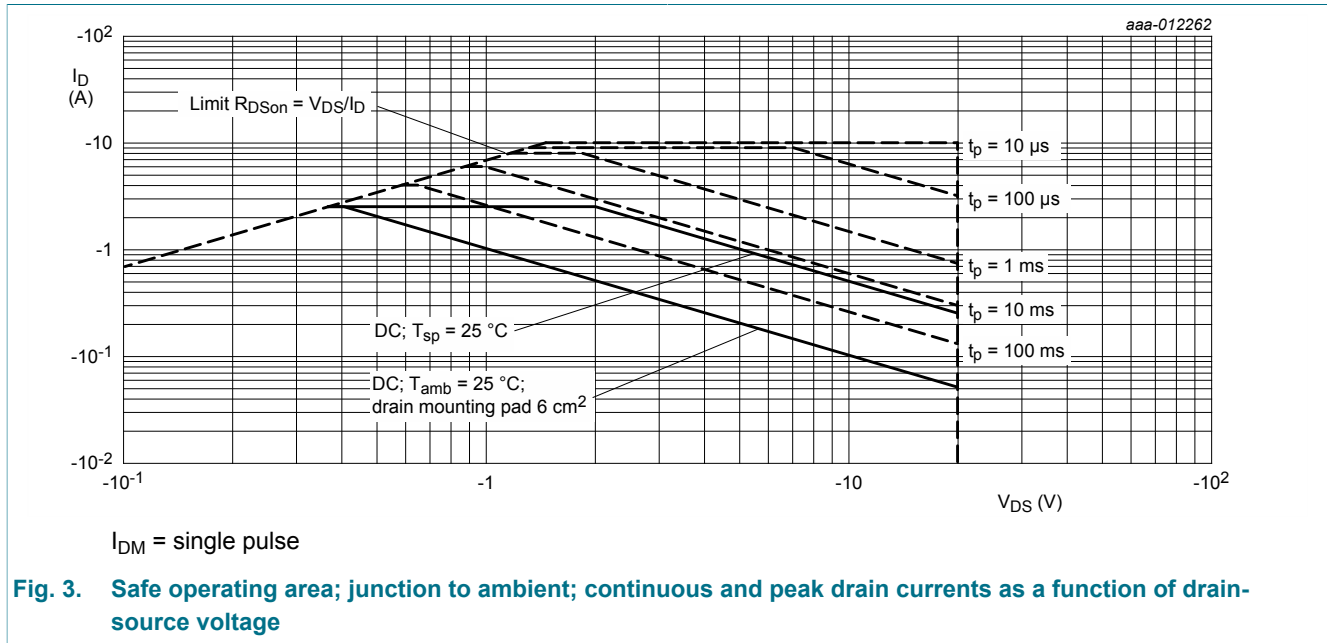


Fig. 2. Normalized continuous drain current as a function of junction temperature

$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100 \%$$



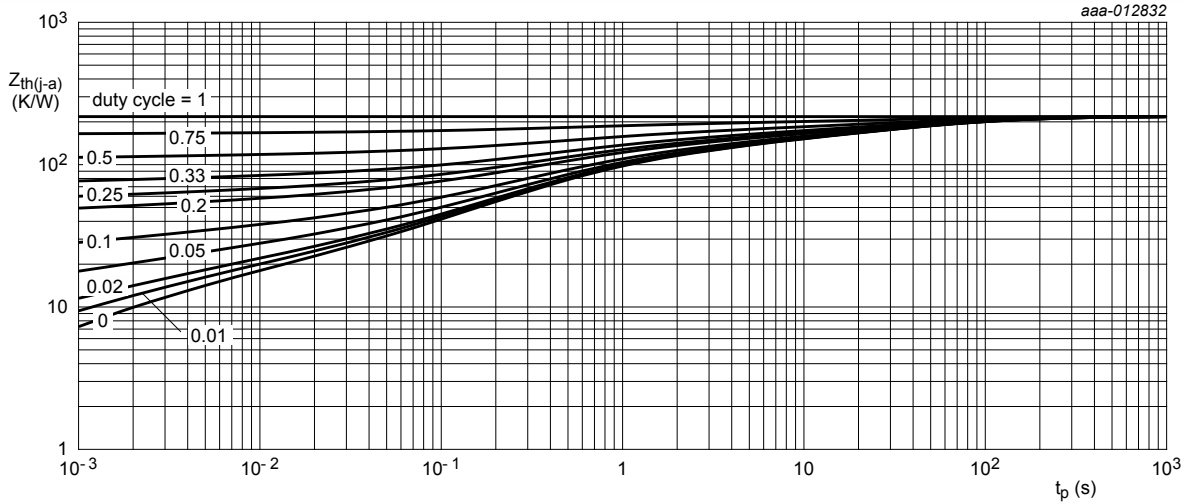
## 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	217	255	K/W
			[2]	-	105	124	K/W
		in free air; $t \leq 5\text{ s}$	[2]	-	73	86	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	20	25	K/W

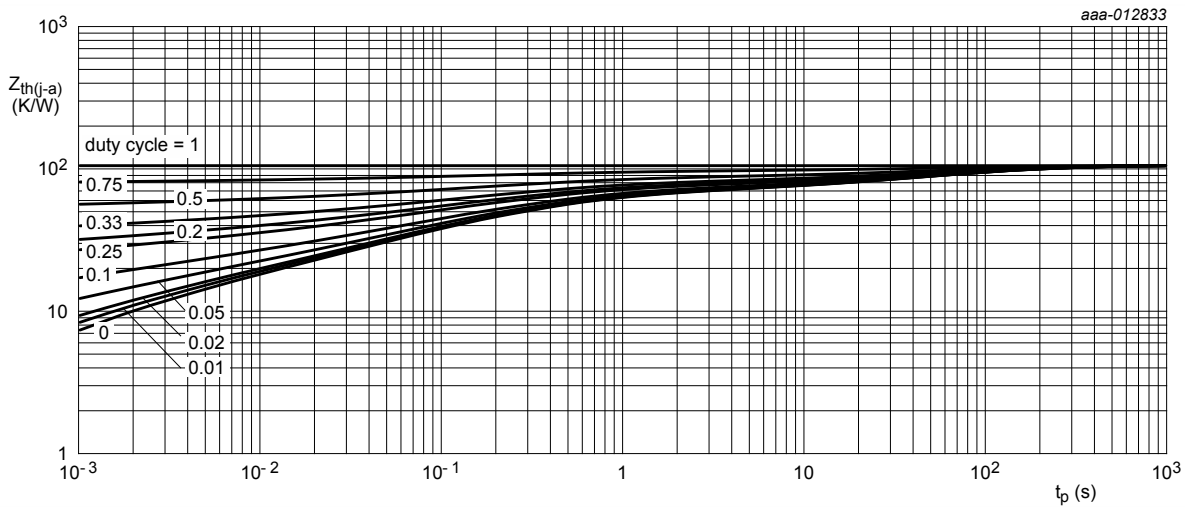
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain  $6\text{ cm}^2$ .



FR4 PCB, standard footprint

**Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



FR4 PCB, mounting pad for drain  $6 \text{ cm}^2$

**Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**

## 10. Characteristics

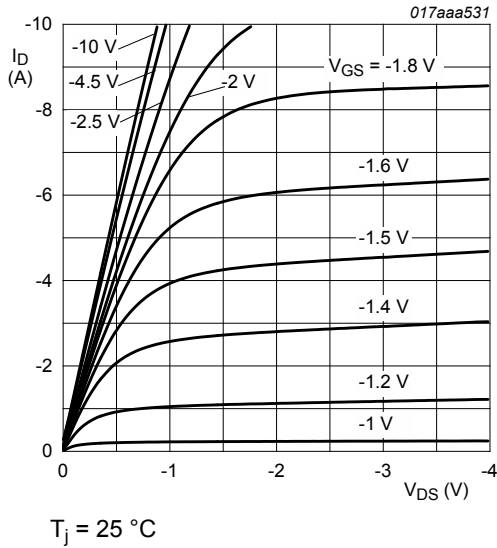
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = -250 \mu A$ ; $V_{GS} = 0 V$ ; $T_j = 25^\circ C$	-20	-	-	V
$V_{GSth}$	gate-source threshold voltage	$I_D = -250 \mu A$ ; $V_{DS} = V_{GS}$ ; $T_j = 25^\circ C$	-0.47	-0.68	-0.9	V
$I_{DSS}$	drain leakage current	$V_{DS} = -20 V$ ; $V_{GS} = 0 V$ ; $T_j = 25^\circ C$	-	-	-1	$\mu A$
$I_{GSS}$	gate leakage current	$V_{GS} = 12 V$ ; $V_{DS} = 0 V$ ; $T_j = 25^\circ C$	-	-	100	nA
		$V_{GS} = -12 V$ ; $V_{DS} = 0 V$ ; $T_j = 25^\circ C$	-	-	-100	nA
$R_{DSon}$	drain-source on-state resistance	$V_{GS} = -4.5 V$ ; $I_D = -2.5 A$ ; $T_j = 25^\circ C$	-	77	102	m $\Omega$
		$V_{GS} = -4.5 V$ ; $I_D = -2.4 A$ ; $T_j = 150^\circ C$	-	110	146	m $\Omega$
		$V_{GS} = -2.5 V$ ; $I_D = -2.2 A$ ; $T_j = 25^\circ C$	-	95	125	m $\Omega$
		$V_{GS} = -1.8 V$ ; $I_D = -1 A$ ; $T_j = 25^\circ C$	-	120	156	m $\Omega$
$g_{fs}$	forward transconductance	$V_{DS} = -10 V$ ; $I_D = -2 A$ ; $T_j = 25^\circ C$	-	15	-	S
$R_G$	internal gate resistance (AC)	$f = 1 MHz$	-	41	-	$\Omega$
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$V_{DS} = -10 V$ ; $I_D = -2.5 A$ ; $V_{GS} = -4.5 V$ ; $T_j = 25^\circ C$	-	5	7.5	nC
$Q_{GS}$	gate-source charge		-	0.7	-	nC
$Q_{GD}$	gate-drain charge		-	0.9	-	nC
$C_{iss}$	input capacitance	$V_{DS} = -10 V$ ; $f = 1 MHz$ ; $V_{GS} = 0 V$ ; $T_j = 25^\circ C$	-	550	-	pF
$C_{oss}$	output capacitance		-	63	-	pF
$C_{rss}$	reverse transfer capacitance		-	53	-	pF
$t_{d(on)}$	turn-on delay time		$V_{DS} = -10 V$ ; $I_D = -2.5 A$ ; $V_{GS} = -4.5 V$ ; $R_{G(ext)} = 6 \Omega$ ; $T_j = 25^\circ C$	-	6	-
$t_r$	rise time	-		14	-	ns
$t_{d(off)}$	turn-off delay time	-		120	-	ns
$t_f$	fall time	-		50	-	ns
<b>Source-drain diode</b>						
$V_{SD}$	source-drain voltage	$I_S = -0.9 A$ ; $V_{GS} = 0 V$ ; $T_j = 25^\circ C$	-	-0.8	-1.2	V

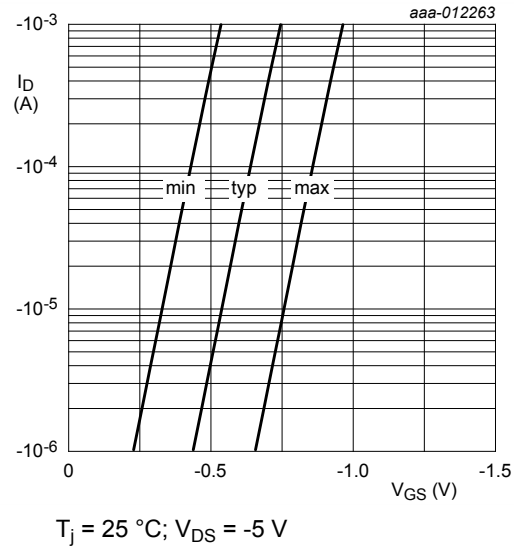
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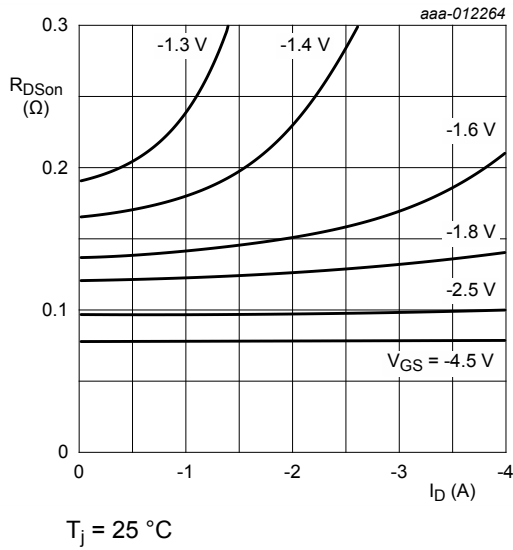
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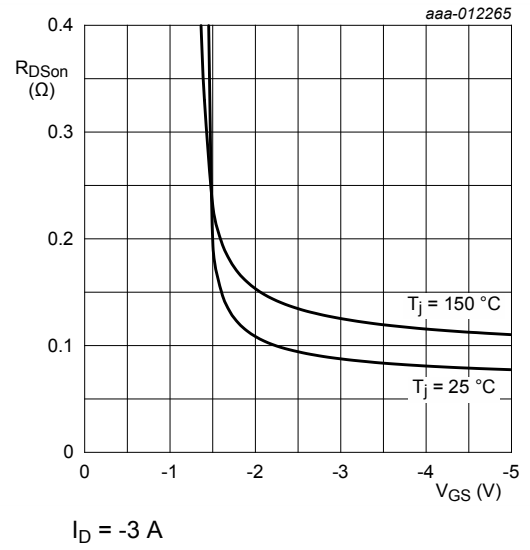
**Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values**



**Fig. 7. Sub-threshold drain current as a function of gate-source voltage**



**Fig. 8. Drain-source on-state resistance as a function of drain current; typical values**



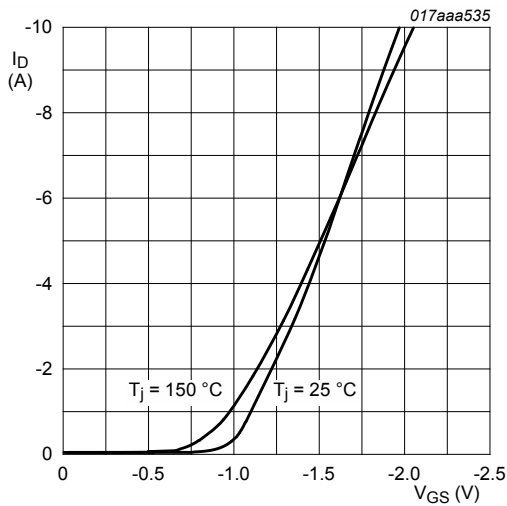
**Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values**



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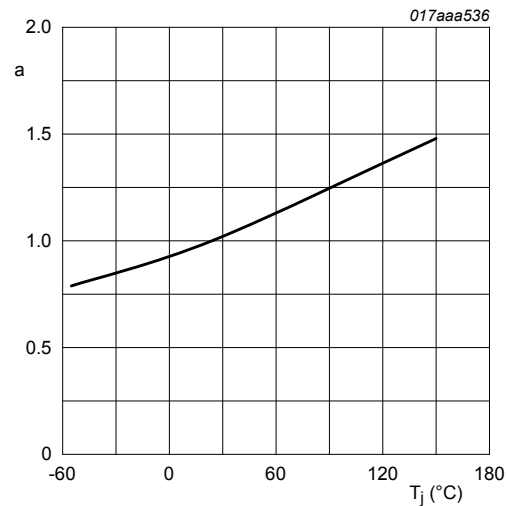
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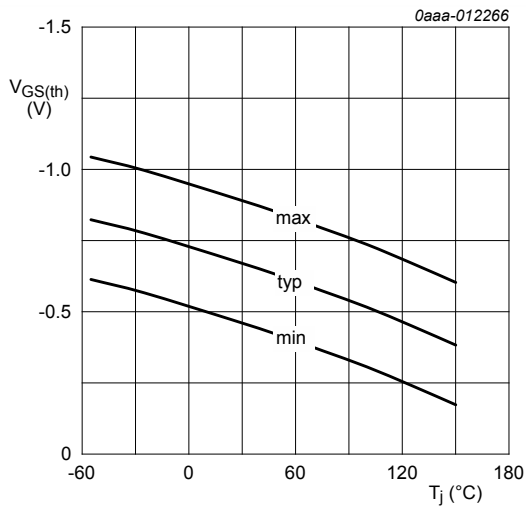
$$V_{DS} > I_D \times R_{DSon}$$

**Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values**



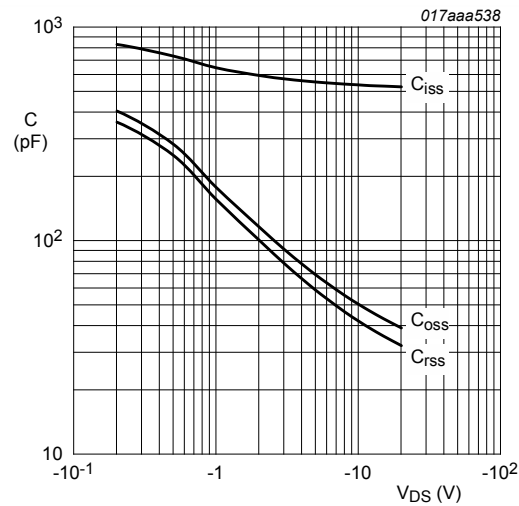
**Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values**

$$a = \frac{R_{DSon}}{R_{DSon(25^\circ C)}}$$



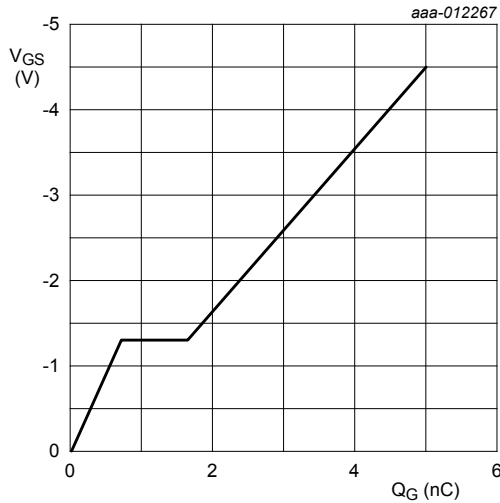
$$I_D = 0.25 \text{ mA}; V_{DS} = V_{GS}$$

**Fig. 12. Gate-source threshold voltage as a function of junction temperature**



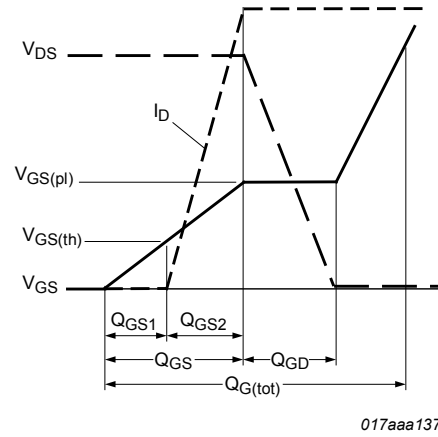
$$f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}$$

**Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values**

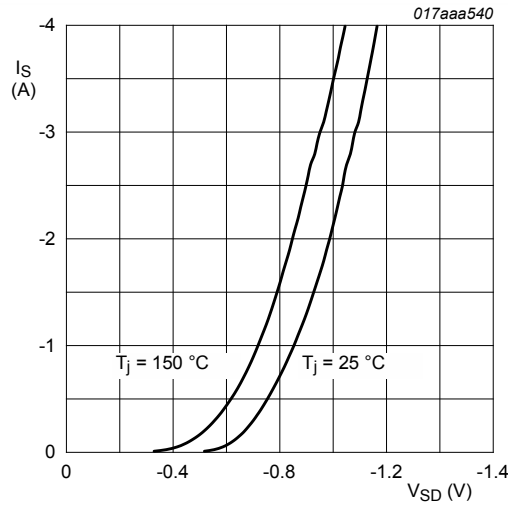


$I_D = -2.8$  A;  $V_{DS} = -10$  V;  $T_{amb} = 25$  °C

**Fig. 14. Gate-source voltage as a function of gate charge; typical values**



**Fig. 15. Gate charge waveform definitions**



$V_{GS} = 0$  V

**Fig. 16. Source current as a function of source-drain voltage; typical values**

## 11. Test information

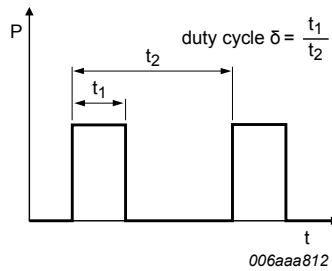


Fig. 17. Duty cycle definition

## 12. Package outline

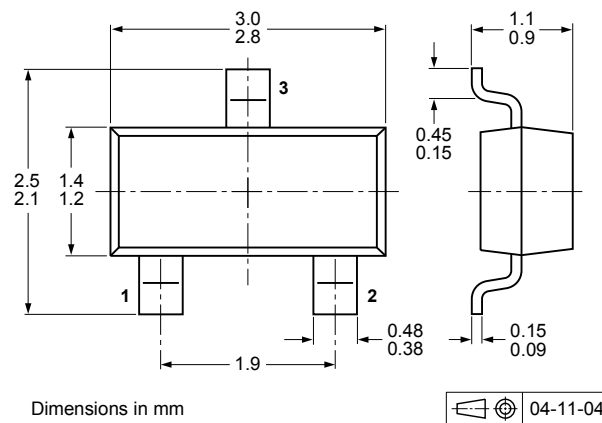
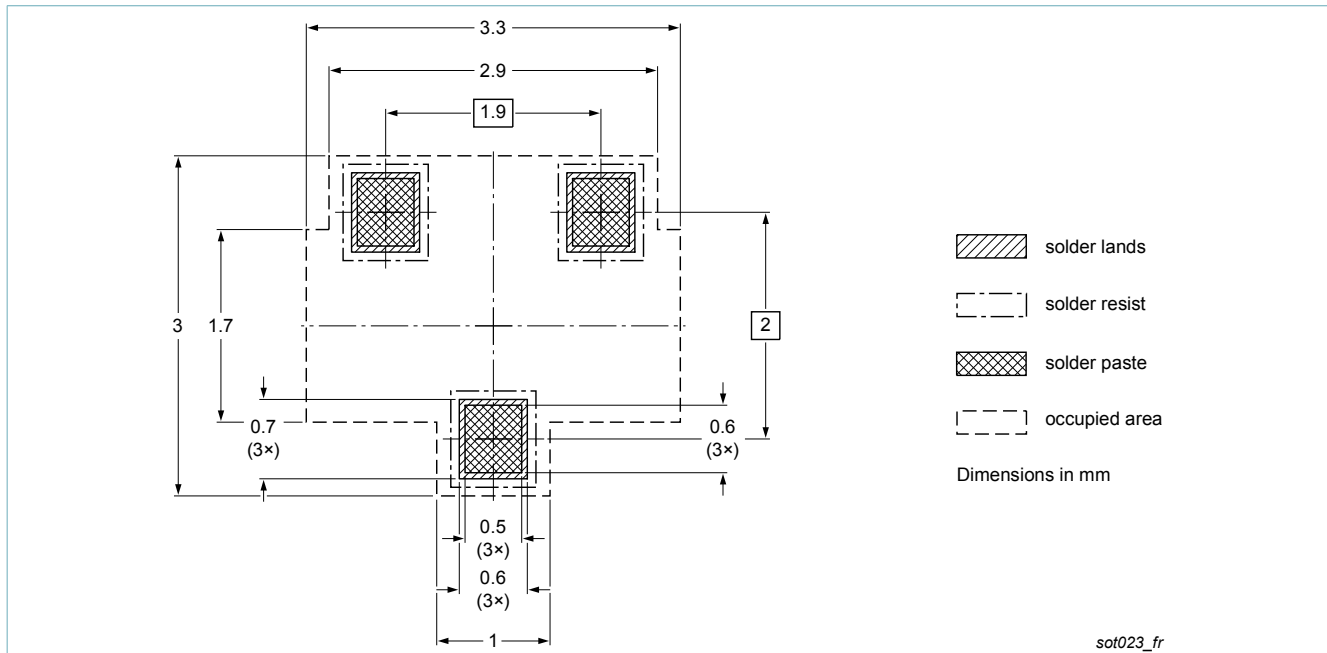
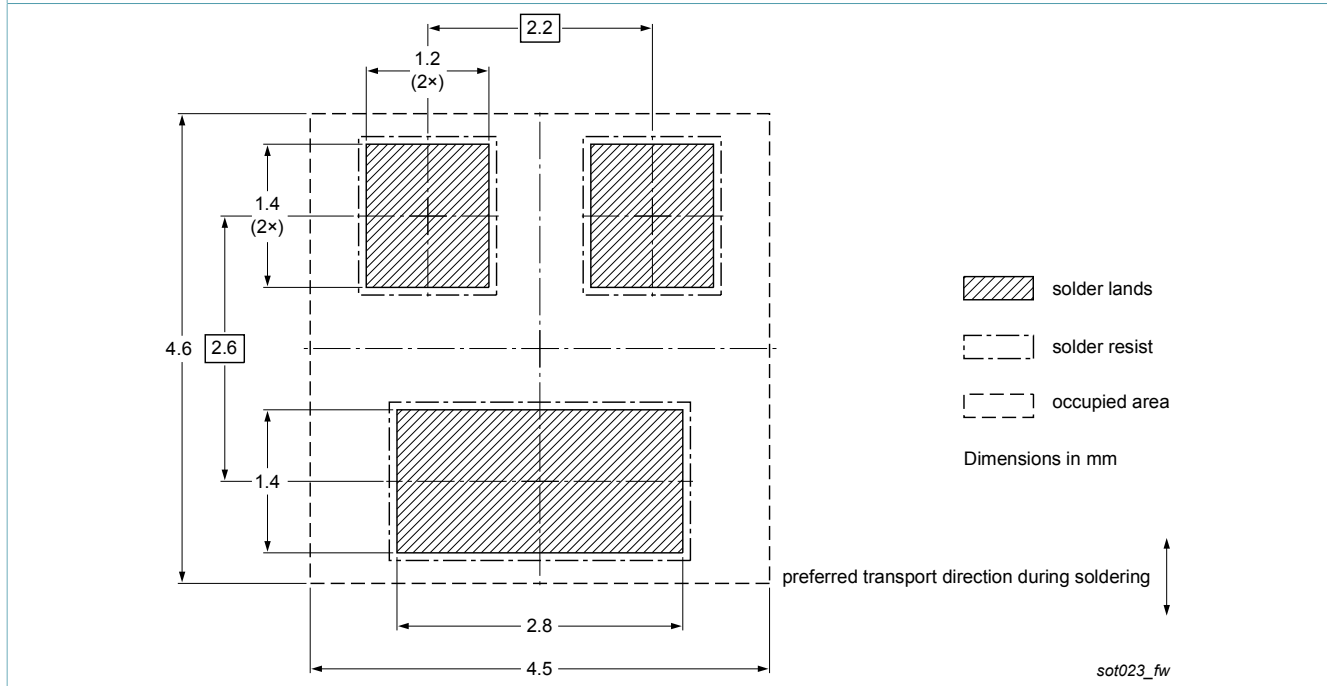


Fig. 18. Package outline TO-236AB (SOT23)

**13. Soldering**



**Fig. 19. Reflow soldering footprint for TO-236AB (SOT23)**



**Fig. 20. Wave soldering footprint for TO-236AB (SOT23)**

## 14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMV75UP v.1	20140425	Product data sheet	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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